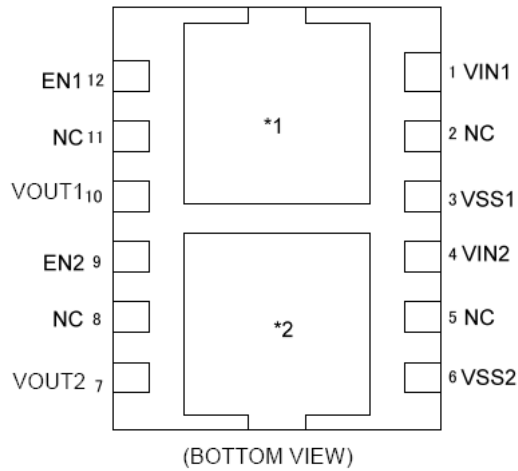
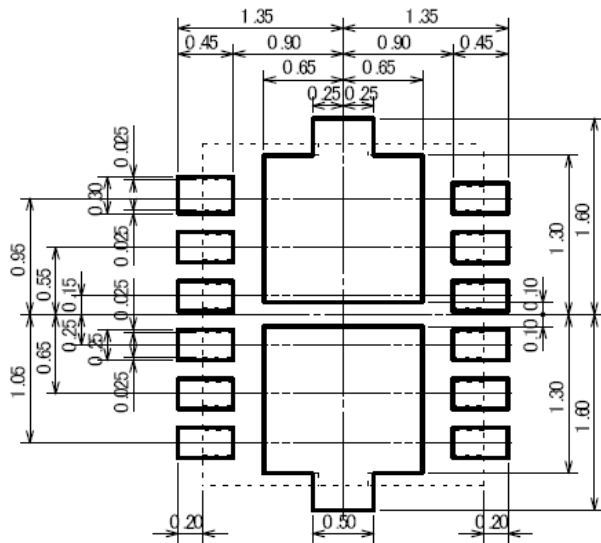


PIN CONFIGURATION

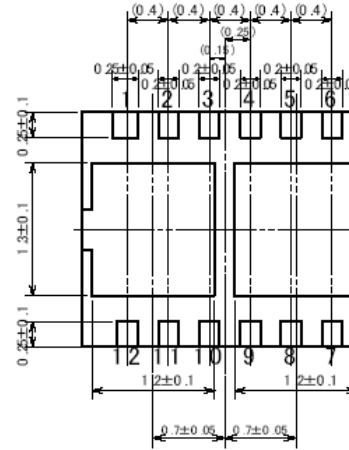
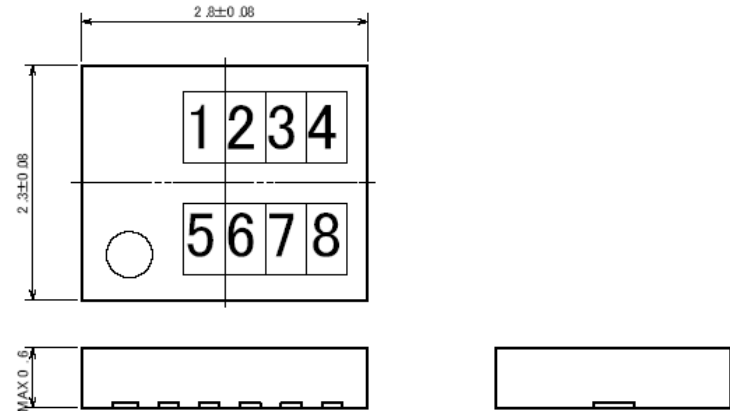


USP-12B01 Reference Pattern Layout



PACKAGING INFORMATION

● USP-12B01



■ Lead Treatment: Au 0.3 μ m Min.

*1: Soldering fillet surface is not formed because the sides of the pins are not plated.

*2: Pin No. 1 is wider than the other pins.

20/1 Unit : mm